

3.5x2.8 mm INFRARED EMITTING DIODE

Part Number: AA3528F3C

Features

• Mechanically and spectrally matched to the phototransistor.

• Package : 1500pcs / reel.

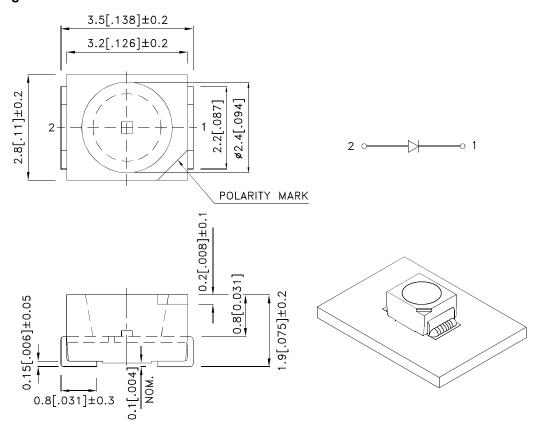
• Moisture sensitivity level : level 4.

• RoHS compliant.

Description

F3 Made with Gallium Arsenide Infrared Emitting diodes.

Package Dimensions



All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.

Specifications are subject to change without notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	Po (mW/sr) [2] @ 20mA *50mA		Viewing Angle [1]
			Min.	Тур.	201/2
AA3528F3C	F3 (GaAs)	WATER CLEAR	1.6	3	- 120°
			*2.6	*8	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. * Luminous intensity with asterisk is measured at 50mA;Radiant Intensity/ luminous flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Parameter	P/N	Symbol	Тур.	Max.	Units	Test Conditions	
Forward Voltage [1]	F3	VF	1.2	1.6	V	IF=20mA	
Reverse Current	F3	lr		10	uA	V _R = 5V	
Capacitance	F3	С	90		pF	VF=0V;f=1MHz	
Peak Spectral Wavelength	F3	λP	940		nm	IF=20mA	
Spectral Bandwidth	F3	Δλ1/2	50		nm	IF=20mA	

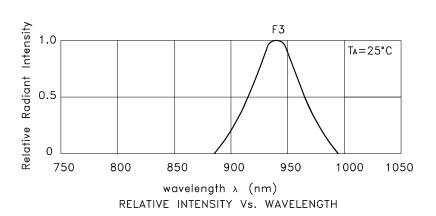
Note: 1. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

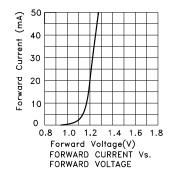
, woodate maximum ratings at 171 20 0						
Parameter	Symbol	F3	Units			
Power dissipation	Po	80	mW			
DC Forward Current	lF	50	mA			
Peak Forward Current [1]	iFS	1.2	А			
Reverse Voltage	VR	5	V			
Operating Temperature	TA	-40 To +85	°C			
Storage Temperature	Тѕтс	-40 To +85	°C			

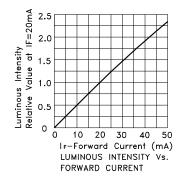
1. 1/100 Duty Cycle, 10µs Pulse Width.

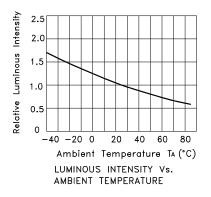
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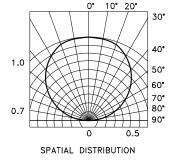


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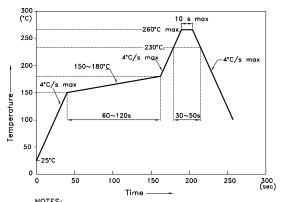
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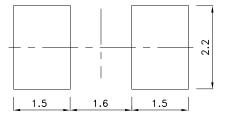
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

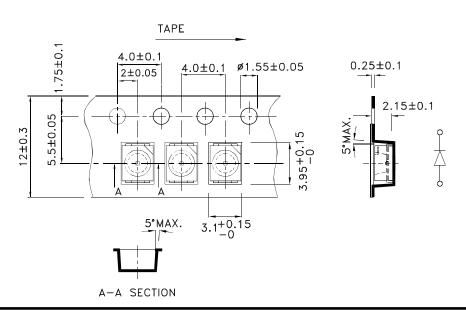


NOTES: 1.We recommend the reflow temperature $245^{\circ}C(+/-5^{\circ}C)$.The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

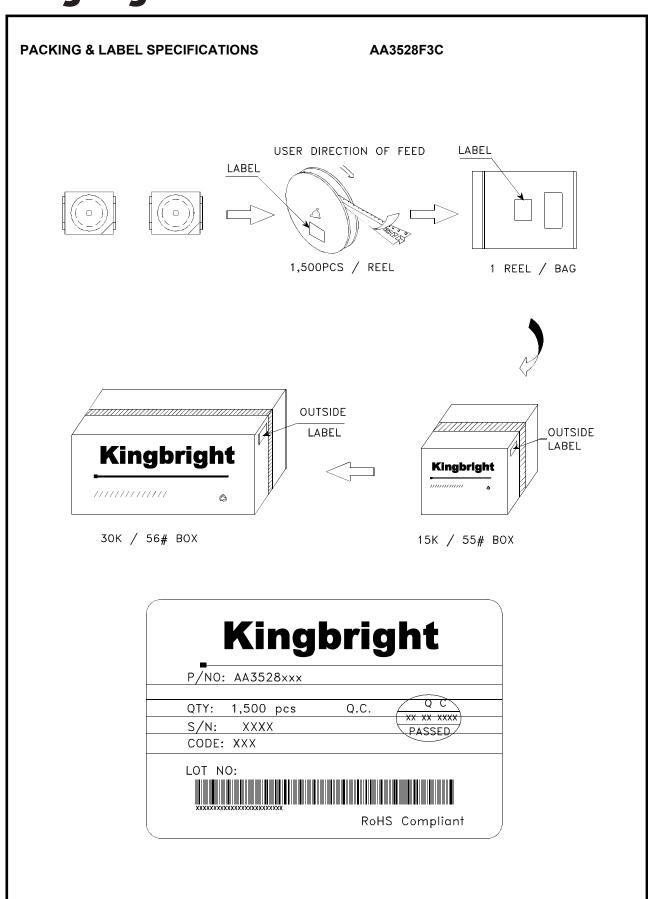
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Specifications (Units: mm)



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